

**Storage and Process Instructions:**

For parts exposed to greater than 60% RH, it is recommended parts be baked at 125°C for 3-5 hours prior to SMT reflow process. If unsure of RH exposure, it is recommend to bake at the above temperature and time prior to SMT reflow process.

**SPECIFICATIONS:**

**ELECTRICAL:**

- RATED CURRENT: 5A
- RATED VOLTAGE: 300VDC
- WITHSTANDING VOLTAGE: 500VAC (rms) FOR 1 MIN
- INSULATION RESISTANCE: > 1,000 mΩ at 500VDC
- CONTACT RESISTANCE: 13mOhms MAX
- DIELECTRIC STRENGTH: 1000VAC FOR 1 MIN
- OPERATING TEMPERATURE: -55°C TO +105°C

**MATERIALS:**

- SHELL: NICKEL PLATED STEEL
- BRACKET: NICKEL PLATED STEEL
- INSULATOR: NYLON 6T, UL 94V-0, BLACK
- PROCESS TEMP: 260°C
- INSULATOR: PATONE #322C, COLOR=Pc99
- CONTACT: TIN PLATED PHOSPHOR BRONZE
- GOLD FLASH MATING AREA
- TIN PLATED SOLDER AREA

RoHS COMPLIANT

UNITS = inch [mm]

DO NOT SCALE FROM DRAWING



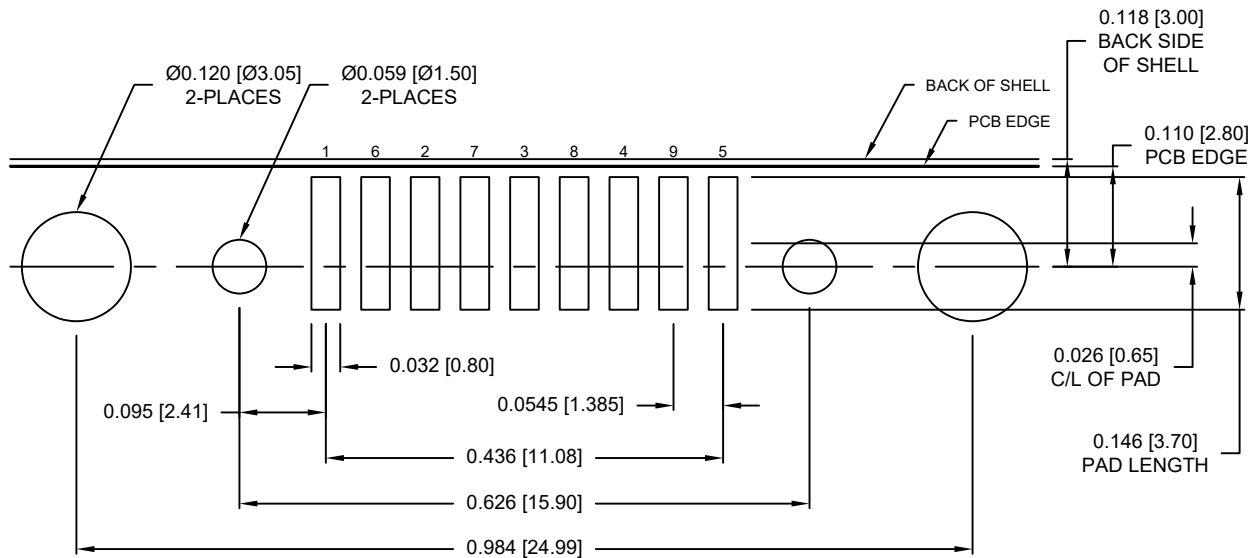
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF NorComp AND SHALL NOT BE REPRODUCED, COPIED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS WITHOUT WRITTEN PERMISSION.

DRAWN:  
C. SMITH

DATE:  
03/30/2009

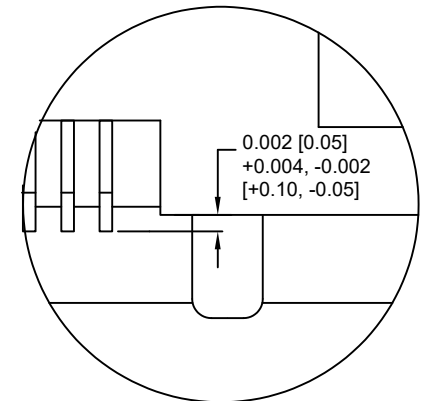
NorComp

SCALE: NTS	SHEET 1	OF 2	REV 15
DWG NO. 190-009-263R001			



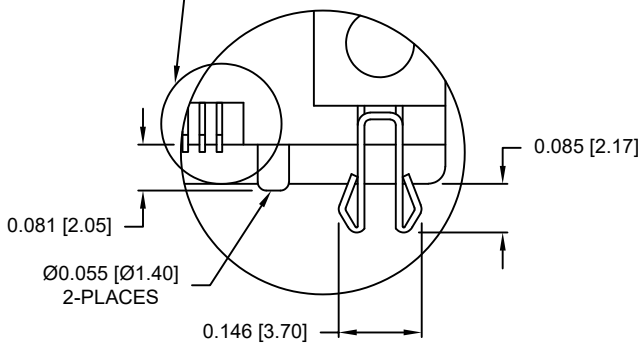
**RECOMMENDED PCB LAYOUT**

CONTACT ARRANGEMENT  
1 6 2 7 3 8 4 9 5

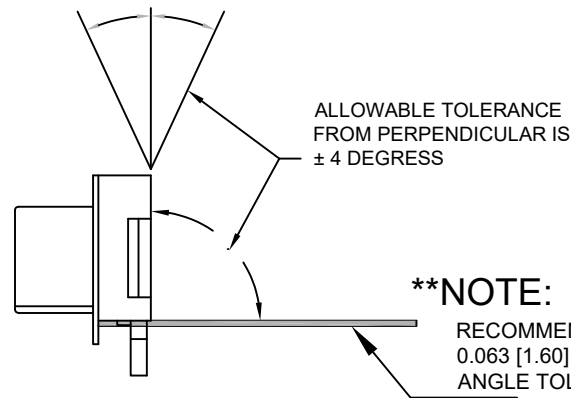


**DETAIL "B"**  
CONTACT COPLANARITY

SEE DETAIL "B"  
FOR CONTACT  
COPLANARITY



**DETAIL "A"**



**\*\*NOTE:**  
RECOMMENDED PCB THICKNESS IS  
0.063 [1.60] ± 0.002 [0.05] TO MAINTAIN  
ANGLE TOLERANCE

**RoHS COMPLIANT**

UNITS = inch [mm]

**DO NOT SCALE FROM DRAWING**



THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF NorComp AND SHALL NOT BE REPRODUCED, COPIED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS WITHOUT WRITTEN PERMISSION.

DRAWN:  
**C. SMITH**

DATE:  
**03/30/2009**

**NorComp**

SCALE:  
NTS

SHEET OF  
2 2

REV  
15

DWG NO.

**190-009-263R001**